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TO THE ASSISTANT COMMISSIONER FOR PATENTS

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Documents or copy thereof.

JC972 U.S. PTO
09/804814
03/13/01

1. Name of conveying party(ies): (If multiple assignors, list numerically)

1. Hideaki Fukuda 2. Hiroki Arai

Additional name(s) of conveying party(ies) attached?

() Yes (X) No

2. Name and address of receiving party(ies):

Name: ASM JAPAN K.K.

Address: 23-1, 6-chome, Nagayama, Tama-shi, Tokyo
206-0025 Japan

Additional name(s) of receiving party(ies) attached?

() Yes (X) No

3. Nature of conveyance:

- (X) Assignment
() Merger
() Security Agreement
() Change of Name
() Other:

Execution Date: (If multiple assignors, list execution dates in numerical order corresponding to numbers indicated in 1 above) 1. 03/09/01 2. 03/09/01

4. Application number(s) or Patent number(s):

(X) Application(s) filed herewith
Execution Date(s): 1. 03/09/01 2. 03/09/01() Patent Application No.:
Filing Date:() Patent No.:
Issue Date:

Additional numbers attached? () Yes (X) No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Gordon H. Olson
KNOBBE, MARTENS, OLSON & BEAR, LLP
Customer No. 20,995
Internal Address: Sixteenth Floor
Street Address: 620 Newport Center Drive
City: Newport Beach State: CA ZIP: 92660
Attorney's Docket No.: ASMJP.092AUS

7. Total fee (37 CFR 3.41): \$40.00

(X) Enclosed
() Authorized to be charged to deposit account

8. Deposit account number: 11-1410

Please charge this account for any additional fees which may be required, or credit any overpayment to this account.

6. Total number of applications and patents involved: 1

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document.

Gordon H. Olson

Name of Person Signing

Signature

March 13, 2001

Date

20,319

Registration No.

Total number of pages including cover sheet, attachments and document: 2

Mail documents to be recorded with required cover sheet information to:

Assistant Commissioner for Patents
Box Assignments
Washington, D.C. 20231

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PATENT
REEL: 011604 FRAME: 0031

Application No.: Unknown
Filing Date: Herewith

PATENT
Client Code: ASMJP.092AUS
Page 1

ASSIGNMENT

WHEREAS, We, Hideaki Fukuda, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, and Hiroki Arai, a Japanese, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, have invented certain new and useful improvements in a METHOD OF FORMING THIN FILM ONTO SEMICONDUCTOR SUBSTRATE which we have filed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, ASM JAPAN K. K.(hereinafter "ASSIGNEE"), a Japan Corporation, with its principal place of business at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 9 day of March, 2001

Hideaki Fukuda
Hideaki Fukuda

This 9 day of March, 2001

Hiroki Arai
Hiroki Arai

Shinichi Kizaki
Witness

Witness

Application No.: Unknown
Filing Date: Herewith

PATENT
Client Code: ASMJP.092AUS
Page 1

ASSIGNMENT

WHEREAS, We, Hideaki Fukuda, a Japanese citizen, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, and Hiroki Arai, a Japanese, residing at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, have invented certain new and useful improvements in a METHOD OF FORMING THIN FILM ONTO SEMICONDUCTOR SUBSTRATE which we have filed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, ASM JAPAN K. K. (hereinafter "ASSIGNEE"), a Japan Corporation, with its principal place of business at 23-1, 6-chome, Nagayama, Tama-shi, Tokyo 206-0025 Japan, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

This 9 day of March, 2001, Hideaki Fukuda
Hideaki Fukuda

This 9 day of March, 2001, Hiroki Arai
Hiroki Arai

Shinichi Kizaki
Witness

Witness

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